SNx4LVC157A Quadruple 2-Line to 1-Line Data Selectors/Multiplexers

1 Features

- Operate from 1.65V to 3.6V
- Specified from –40°C to 85°C, –40°C to 125°C, and –55°C to 125°C
- Inputs accept voltages to 5.5V
- Max t_{pd} of 5.2ns at 3.3V
- Typical V_{OLP} (output ground bounce) <0.8V at V_{CC} = 3.3V, T_A = 25°C
- Typical V_{OHV} (output V_{OH} undershoot) >2V at V_{CC} = 3.3V, T_A = 25°C
- Latch-up performance exceeds 250mA per JESD 17
- ESD protection exceeds JESD 22
  - 2000V human-body model (A114-A)
  - 1000V charged-device model (C101)

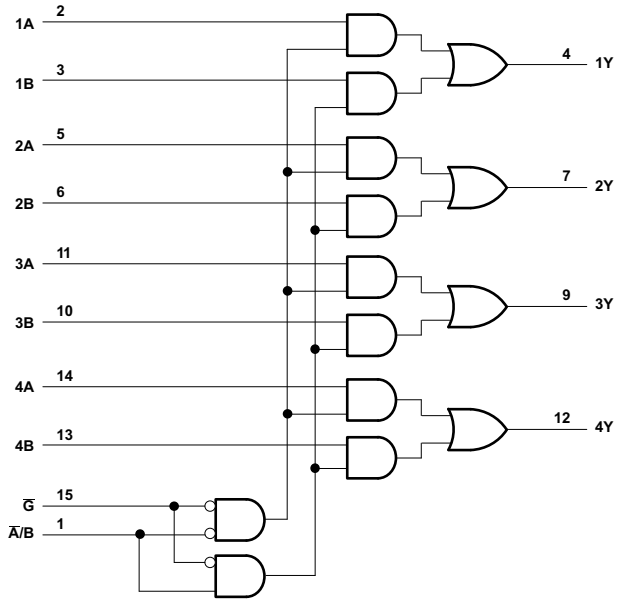
2 Description

These quadruple 2-line to 1-line data selectors/multiplexers are designed for 1.65V to 3.6V V_{CC} operation.

Device Information

PART NUMBER	PACKAGE(1)	PACKAGE SIZE(2)	BODY SIZE(3)
SNx4LVC157A	BQB (WQFN, 16)	3.5mm × 2.5mm	3.5mm × 2.5mm
	D (SOIC, 16)	9.90 mm × 6mm	9.90 mm × 3.90 mm
	DB (SSOP, 16)	6.20 mm × 7.8mm	6.20 mm × 5.30 mm
	NS (SOP, 16)	5mm × 6.4mm	5mm × 4.4mm
	PW (TSSOP, 16)	5.00 mm × 6.4mm	5.00 mm × 4.40 mm
	RGY (VQFN, 16)	4mm × 3.5mm	4mm × 3.5mm

(1) For more information, see Mechanical, Packaging, and Orderable Information.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.
(3) The body size (length × width) is a nominal value and does not include pins.



Logic Diagram (Positive Logic)

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3 Pin Configuration and Functions

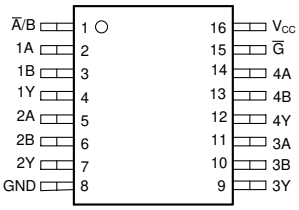


Figure 3-1. SN54LVC157A J or W Package, 16-Pin CDIP or CFP; SN74LVC157A D, DB, NS, or, PW Package, 16-Pin SOIC, SSOP, SOP, or TSSOP (Top View)

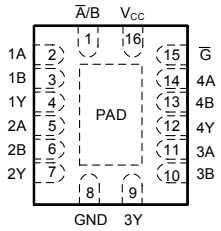


Figure 3-2. SN74LVC157A BQB or RGY Package, 16-Pin WQFN or VQFN (Top View)

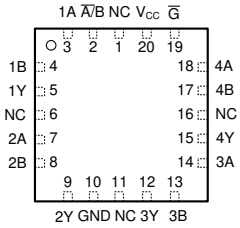


Figure 3-3. SN54LVC157A FK Package, 16-Pin LCCC (Top View)

Table 3-1. Pin Functions

PIN		TYPE[1]	DESCRIPTION
NAME	NO.		
$\overline{A}$/B	1	I	Address select
1A	2	I	Channel 1, data input A
1B	3	I	Channel 1, data input B
1Y	4	O	Channel 1, data output
2A	5	I	Channel 2, data input A
2B	6	I	Channel 2, data input B
2Y	7	O	Channel 2, data output
GND	8	G	Ground
3Y	9	O	Channel 3, data output
3B	10	I	Channel 3, data input B
3A	11	I	Channel 3, data input A
4Y	12	O	Channel 4, data output
4B	13	I	Channel 4, data input B
4A	14	I	Channel 4, data input A
$\overline{G}$	15	I	Output strobe, active low
V_{CC}	16	P	Positive supply
Thermal pad[2]		—	The thermal pad can be connected to GND or left floating. Do not connect to any other signal or supply.

(1) Signal Types: I = Input, O = Output, I/O = Input or Output, P = Power, G = Ground.
(2) WBQB package only.

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	6.5	V
V_I	Input voltage range(1)		–0.5	6.5	V
V_O	Output voltage range(1) (2)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–50	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
T_{stg}	Storage temperature range		–65	150	°C
P_{tot}	Power dissipation(3) (4)	T_A = –40°C to 125°C		500	mW

(1) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(2) The value of V_{CC} is provided in the recommended operating conditions table.
(3) For the D package, above 70°C the value of P_{tot} derates linearly with 8 mW/K.
(4) For the DB, NS, and PW packages, above 60°C the value of P_{tot} derates linearly with 5.5 mW/K.

4.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

4.3 Recommended Operating Conditions, SN54LVC157A

over operating free-air temperature range (unless otherwise noted)(1)

			SN54LVC157A –55 TO 125°C		UNIT
			MIN	MAX	
V_{CC}	Supply voltage	Operating	2	3.6	V
		Data retention only	1.5		
V_{IH}	High-level input voltage	V_{CC} = 2.7V to 3.6V	2		V
V_{IL}	Low-level input voltage	V_{CC} = 2.7V to 3.6V		0.8	V
V_I	Input voltage		0	5.5	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2.7V		–12	mA
		V_{CC} = 3V		–24	
I_{OL}	Low-level output current	V_{CC} = 2.7V		12	mA
		V_{CC} = 3V		24	

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.4 Recommended Operating Conditions, SN74LVC157A

over operating free-air temperature range (unless otherwise noted)(1)

			SN74LVC157A						UNIT
			T_A = 25°C		–40 TO 85°C		–40 TO 125°C		
			MIN	MAX	MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		1.5		
V_{IH}	High-level input voltage	V_{CC} = 1.65V to 1.95V	0.65 × V_{CC}		0.65 × V_{CC}		0.65 × V_{CC}		V
		V_{CC} = 2.3V to 2.7V	1.7		1.7		1.7		
		V_{CC} = 2.7V to 3.6V	2		2		2		
V_{IL}	Low-level input voltage	V_{CC} = 1.65V to 1.95V		0.35 × V_{CC}		0.35 × V_{CC}		0.35 × V_{CC}	V
		V_{CC} = 2.3V to 2.7V		0.7		0.7		0.7	
		V_{CC} = 2.7V to 3.6V		0.8		0.8		0.8	
V_I	Input voltage		0	5.5	0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 1.65V		–4		–4		–4	mA
		V_{CC} = 2.3V		–8		–8		–8	
		V_{CC} = 2.7V		–12		–12		–12	
		V_{CC} = 3V		–24		–24		–24	
I_{OL}	Low-level output current	V_{CC} = 1.65V		4		4		4	mA
		V_{CC} = 2.3V		8		8		8	
		V_{CC} = 2.7V		12		12		12	
		V_{CC} = 3V		24		24		24	
Δt/Δv	Input transition rise and fall rate			10		10		10	ns/V

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.5 Thermal Information

THERMAL METRIC(1)		SN74LVC157A						UNIT
		BQB (WQFN)	D (SOIC)	DB (SSOP)	NS (SOP)	PW (TSSOP)	RGY (VQFN)	
		16 PINS						
$R_{\theta JA}$	Junction-to-ambient thermal resistance	98.8	118.1	82	64	141.8	87.1	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC package thermal metrics* application report.

4.6 Electrical Characteristics, SN54LVC157A

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	SN54LVC157A		UNIT
			–55 TO 125°C		
			MIN	MAX	
V_{OH}	I_{OH} = –100μA	2.7V to 3.6V	V_{CC} – 0.2		V
	I_{OH} = –12mA	2.7V	2.2		
		3V	2.4		
	I_{OH} = –24mA	3V	2.2		

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}	SN54LVC157A –55 TO 125°C MIN	SN54LVC157A –55 TO 125°C MAX	UNIT
V_{OL}		I_{OL} = 100µA		2.7V to 3.6V		0.2	V
		I_{OL} = 12mA		2.7V		0.4	
		I_{OL} = 24mA		3V		0.55	
I_I	All inputs	V_I = 5.5V or GND		3.6V		±5	µA
I_{CC}		V_I = V_{CC} or GND	I_O = 0	3.6V		10	µA
ΔI_{CC}		One input at V_{CC} – 0.6V, Other inputs at V_{CC} or GND		2.7V to 3.6V		500	µA

4.7 Electrical Characteristics, SN74LVC157A

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}	SN74LVC157A T_A = 25°C MIN	SN74LVC157A T_A = 25°C TYP	SN74LVC157A T_A = 25°C MAX	SN74LVC157A –40 TO 85°C MIN	SN74LVC157A –40 TO 85°C MAX	SN74LVC157A –40 TO 125°C MIN	SN74LVC157A –40 TO 125°C MAX	UNIT
V_{OH}		I_{OH} = –100µA		1.65V to 3.6V	V_{CC} – 0.2			V_{CC} – 0.2		V_{CC} – 0.3		V
		I_{OH} = –4mA		1.65V	1.29			1.2		1.05		
		I_{OH} = –8mA		2.3V	1.9			1.7		1.55		
		I_{OH} = –12mA		2.7V	2.2			2.2		2.05		
				3V	2.4			2.4		2.25		
		I_{OH} = –24mA		3V	2.3			2.2		2		
V_{OL}		I_{OL} = 100µA		1.65V to 3.6V			0.1		0.2		0.3	V
		I_{OL} = 4mA		1.65V			0.24		0.45		0.6	
		I_{OL} = 8mA		2.3V			0.3		0.7		0.75	
		I_{OL} = 12mA		2.7V			0.4		0.4		0.6	
		I_{OL} = 24mA		3V			0.55		0.55		0.8	
I_I	All inputs	V_I = 5.5V or GND		3.6V			±1		±5		±20	µA
I_{CC}		V_I = V_{CC} or GND	I_O = 0	3.6V			1		10		40	µA
ΔI_{CC}		One input at V_{CC} – 0.6V, Other inputs at V_{CC} or GND		2.7V to 3.6V			500		500		5000	µA
C_i		V_I = V_{CC} or GND		3.3V		5						pF

4.8 Switching Characteristics, SN54LVC157A

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	SN54LVC157A –55 TO 125°C MIN	SN54LVC157A –55 TO 125°C MAX	UNIT
t_{pd}	A or B	Y	2.7V		6.2	ns
			3.3V ± 0.3V	0.8	5.4	
	$\overline{A}$/B		2.7V		8.2	
			3.3V ± 0.3V	0.8	7	
	$\overline{G}$		2.7V		7.8	
			3.3V ± 0.3V	0.8	6.5	

4.9 Switching Characteristics, SN74LVC157A

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	SN74LVC157A							UNIT
				T_A = 25°C			–40 TO 85°C		–40 TO 125°C		
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	1.8V ± 0.15V	1	5.5	13.5	1	14	1	15.5	ns
			2.5V ± 0.2V	1	3.2	7.4	1	7.9	1	10	
			2.7V	1	3.6	5.7	1	5.9	1	7.4	
			3.3V ± 0.3V	1	3	5	1	5.2	1	6.4	
	$\overline{A}$/B		1.8V ± 0.15V	1	6	15.5	1	16	1	17.5	
			2.5V ± 0.2V	1	3.7	9.6	1	10.1	1	12.2	
			2.7V	1	4.1	7.9	1	8.1	1	10	
			3.3V ± 0.3V	1	3.4	6.6	1	6.8	1	8.4	
	$\overline{G}$		1.8V ± 0.15V	1	5.9	13.5	1	14	1	15.5	
			2.5V ± 0.2V	1	3.5	9.3	1	9.8	1	11.9	
			2.7V	1	3.9	7.6	1	7.8	1	9.3	
			3.3V ± 0.3V	1	3.3	6.3	1	6.5	1	7.9	
$t_{sk(o)}$			1.8V ± 0.15V					2		2.5	ns
			3.3V ± 0.3V					1		1.5	

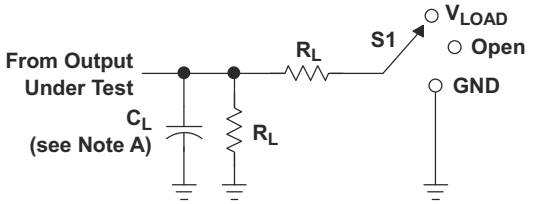
4.10 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10 MHz	1.8V	14[1]	pF
			2.5V	15[1]	
			3.3V	16	

(1) On products compliant to MIL-PRF-38535, this parameter does not apply.

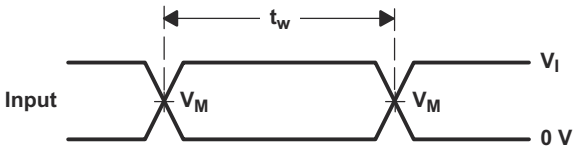
5 Parameter Measurement Information



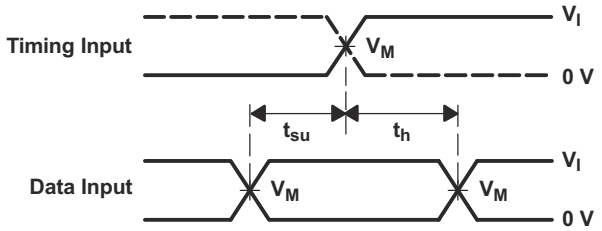
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

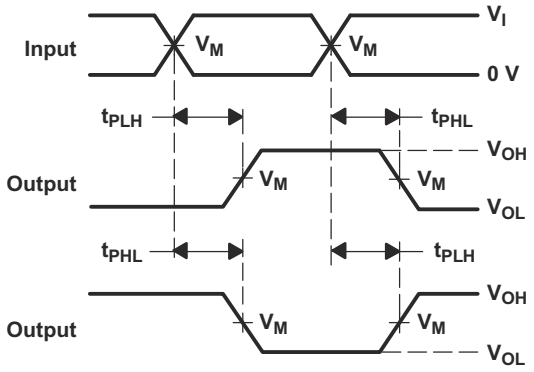
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
1.8 V ± 0.15 V	V_{CC}	≤2 ns	$V_{CC}/2$	2 × V_{CC}	30 pF	1 kW	0.15 V
2.5 V ± 0.2 V	V_{CC}	≤2 ns	$V_{CC}/2$	2 × V_{CC}	30 pF	500 W	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 W	0.3 V
3.3 V ± 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 W	0.3 V



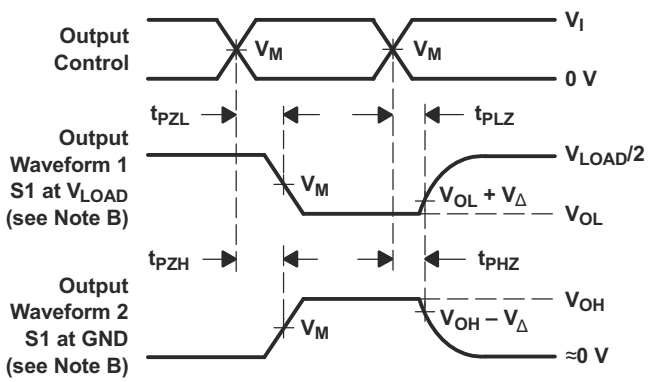
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR≤ 10 MHz, Z_O = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 5-1. Load Circuit and Voltage Waveforms

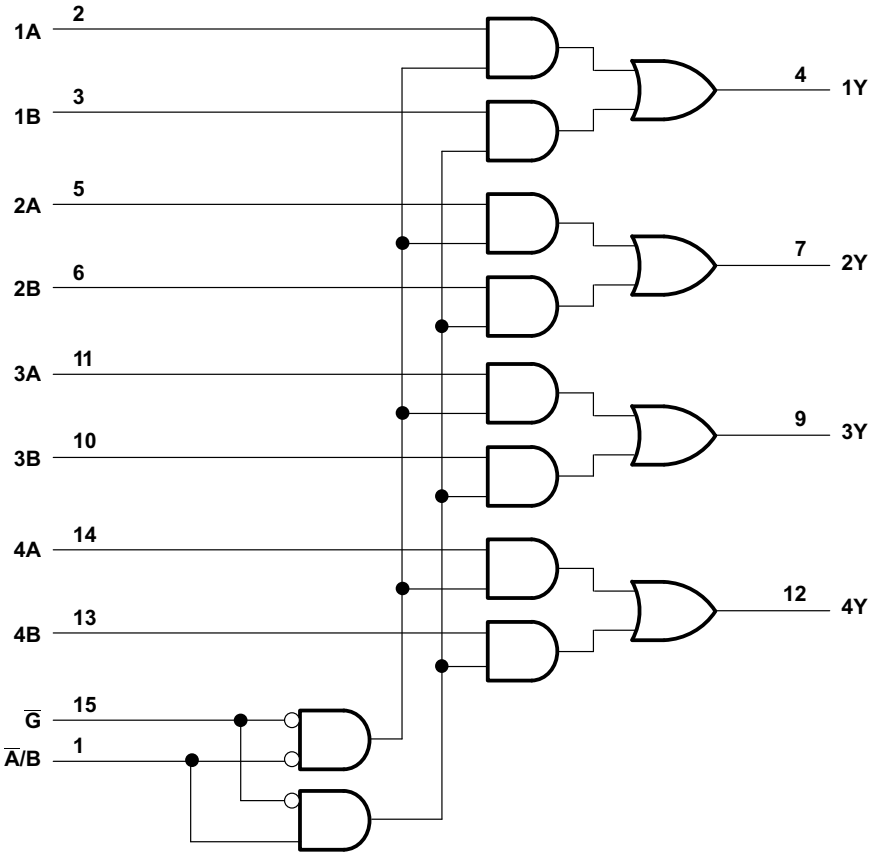
6 Detailed Description

6.1 Overview

The 'LVC157A devices feature a common strobe ($\overline{G}$) input. When $\overline{G}$ is high, all outputs are low. When $\overline{G}$ is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. The 'LVC157A devices provide true data.

Inputs can be driven from either 3.3V or 5V devices. This feature allows the use of these devices as translators in a mixed 3.3V/5V system environment.

6.2 Functional Block Diagram



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, RGY, and W packages.

Figure 6-1. Logic Diagram (Positive Logic)

6.3 Device Functional Modes

Function Table

INPUTS				OUTPUT Y
$\overline{G}$	$\overline{A}$/B	A	B	
H	X	X	X	L
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *Section 4.4* table.

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1µf is recommended; if there are multiple V_{CC} pins, then 0.01µf or 0.022 µf is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1µf and a 1µf are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

7.2 Layout

7.2.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified in Layout Diagram are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC}, whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

7.2.2 Layout Example

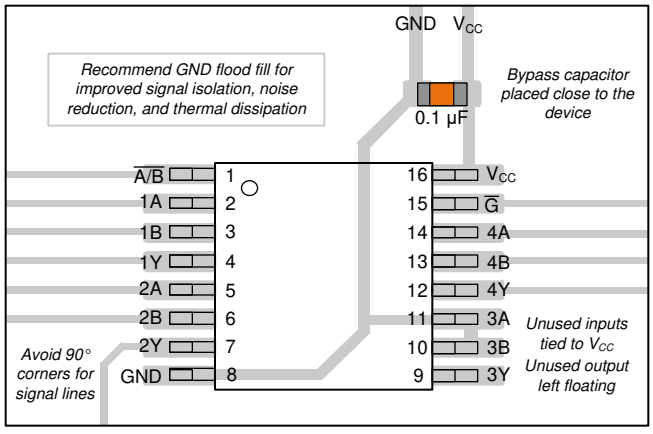


Figure 7-1. Example Layout for the SN74LVC157A

8 Device and Documentation Support

8.1 Documentation Support (Analog)

8.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 8-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54LVC157A	Click here	Click here	Click here	Click here	Click here
SN74LVC157A	Click here	Click here	Click here	Click here	Click here

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

TI Glossary — This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision R (May 2024) to Revision S (December 2024)	Page
• Updated RθJA values: D = 73 to 118.1, PW = 108 to 141.8, RGY = 39 to 87.1; Updated D, PW, and RGY packages for RθJC(top), RθJB, ΨJT, ΨJB, and RθJC(bot), all values in °C/W	5

Changes from Revision Q (December 2010) to Revision R (May 2024)	Page
• Added BQA package to *Package Information* table, *Pin Configuration and Functions* section, and *Thermal Information* table	1
• Added *Device Information* table, *Pin Functions* table, *ESD Ratings* table, *Thermal Information* table, *Device Functional Modes,*Application and Implementation section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section	1

- Deleted machine model from *Features* section....1

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-0050601QEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-0050601QE A SNJ54LVC157AJ	Samples
5962-0050601QFA	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-0050601QF A SNJ54LVC157AW	Samples
SN74LVC157ABQBR	ACTIVE	WQFN	BQB	16	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples
SN74LVC157AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157ADBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples
SN74LVC157ADG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157ADRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157ADRG3	ACTIVE	SOIC	D	16	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157ADRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157ADT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157ANSR	ACTIVE	SOP	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157ANSRE4	ACTIVE	SOP	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC157A	Samples
SN74LVC157APW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples
SN74LVC157APWE4	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples
SN74LVC157APWG4	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples
SN74LVC157APWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples
SN74LVC157APWRE4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC157APWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples
SN74LVC157APWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC157A	Samples
SN74LVC157ARGYR	ACTIVE	VQFN	RGY	16	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LC157A	Samples
SNJ54LVC157AJ	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-0050601QE A SNJ54LVC157AJ	Samples
SNJ54LVC157AW	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-0050601QF A SNJ54LVC157AW	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN54LVC157A, SN74LVC157A :

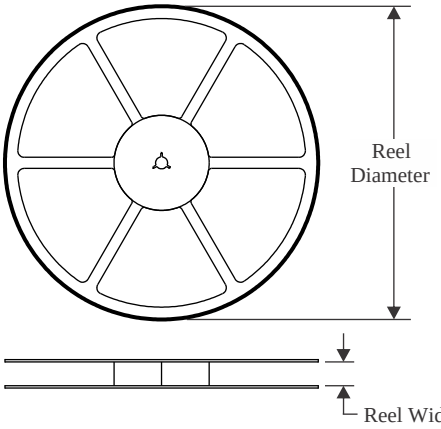
- Catalog : SN74LVC157A
- Automotive : SN74LVC157A-Q1, SN74LVC157A-Q1
- Enhanced Product : SN74LVC157A-EP, SN74LVC157A-EP
- Military : SN54LVC157A

NOTE: Qualified Version Definitions:

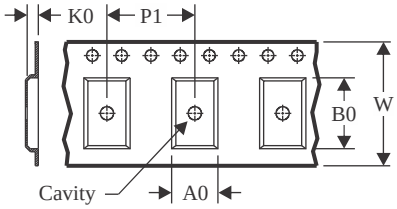
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

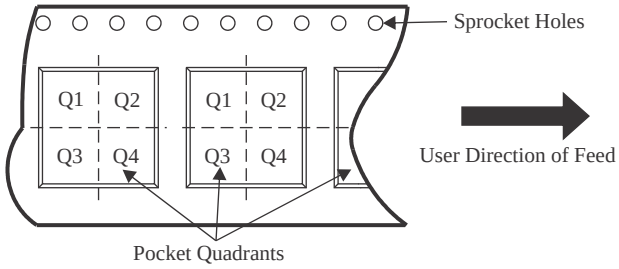


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

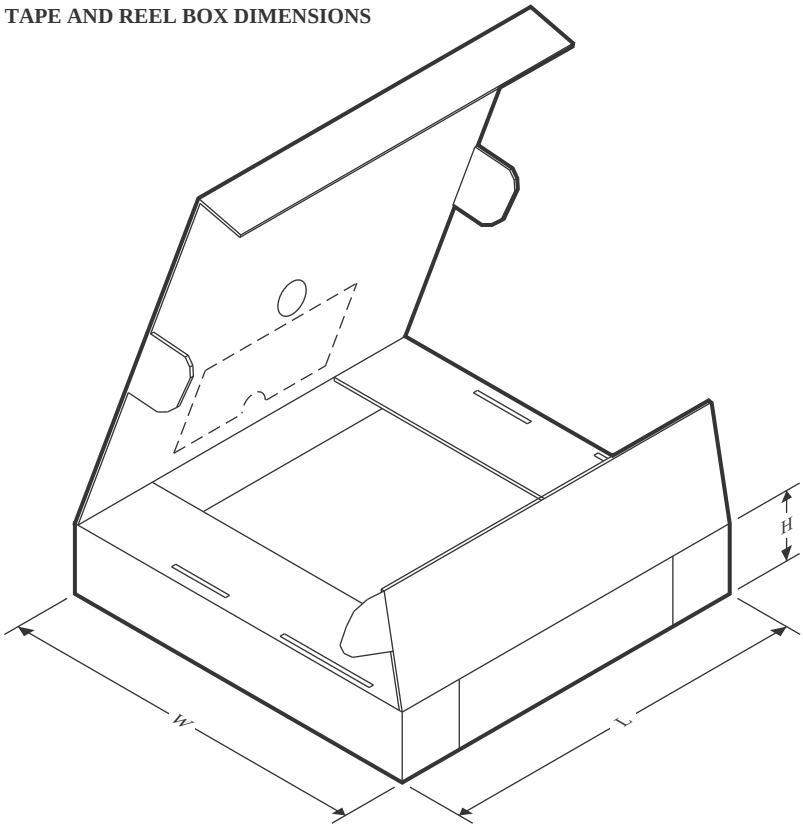
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC157ABQBR	WQFN	BQB	16	3000	180.0	12.4	2.8	3.8	1.2	4.0	12.0	Q1
SN74LVC157ADBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LVC157ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LVC157ADRG3	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
SN74LVC157ADRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LVC157ANSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVC157APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC157APWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC157APWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC157ARGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

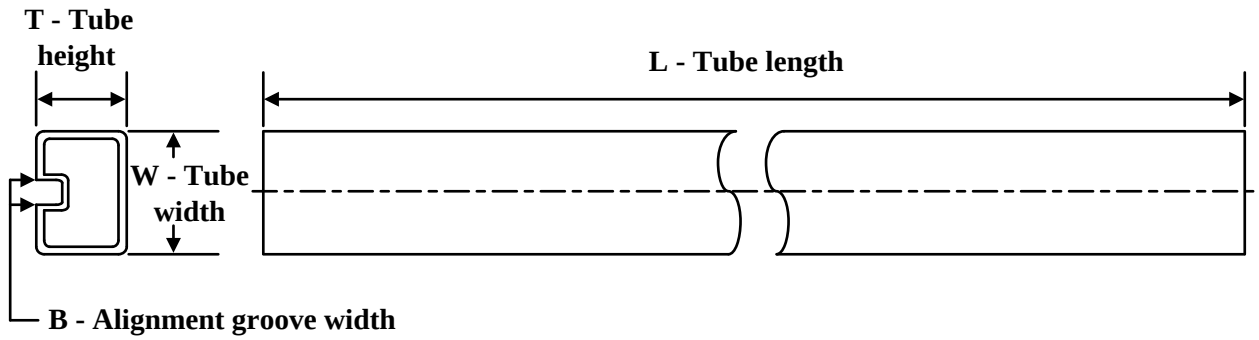
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

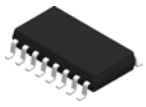
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC157ABQBR	WQFN	BQB	16	3000	210.0	185.0	35.0
SN74LVC157ADBR	SSOP	DB	16	2000	356.0	356.0	35.0
SN74LVC157ADR	SOIC	D	16	2500	353.0	353.0	32.0
SN74LVC157ADRG3	SOIC	D	16	2500	364.0	364.0	27.0
SN74LVC157ADRG4	SOIC	D	16	2500	340.5	336.1	32.0
SN74LVC157ANSR	SOP	NS	16	2000	356.0	356.0	35.0
SN74LVC157APWR	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74LVC157APWRG4	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74LVC157APWT	TSSOP	PW	16	250	356.0	356.0	35.0
SN74LVC157ARGYR	VQFN	RGY	16	3000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-0050601QFA	W	CFP	16	25	506.98	26.16	6220	NA
SN74LVC157AD	D	SOIC	16	40	507	8	3940	4.32
SN74LVC157ADG4	D	SOIC	16	40	507	8	3940	4.32
SN74LVC157APW	PW	TSSOP	16	90	530	10.2	3600	3.5
SN74LVC157APWE4	PW	TSSOP	16	90	530	10.2	3600	3.5
SN74LVC157APWG4	PW	TSSOP	16	90	530	10.2	3600	3.5
SNJ54LVC157AW	W	CFP	16	25	506.98	26.16	6220	NA

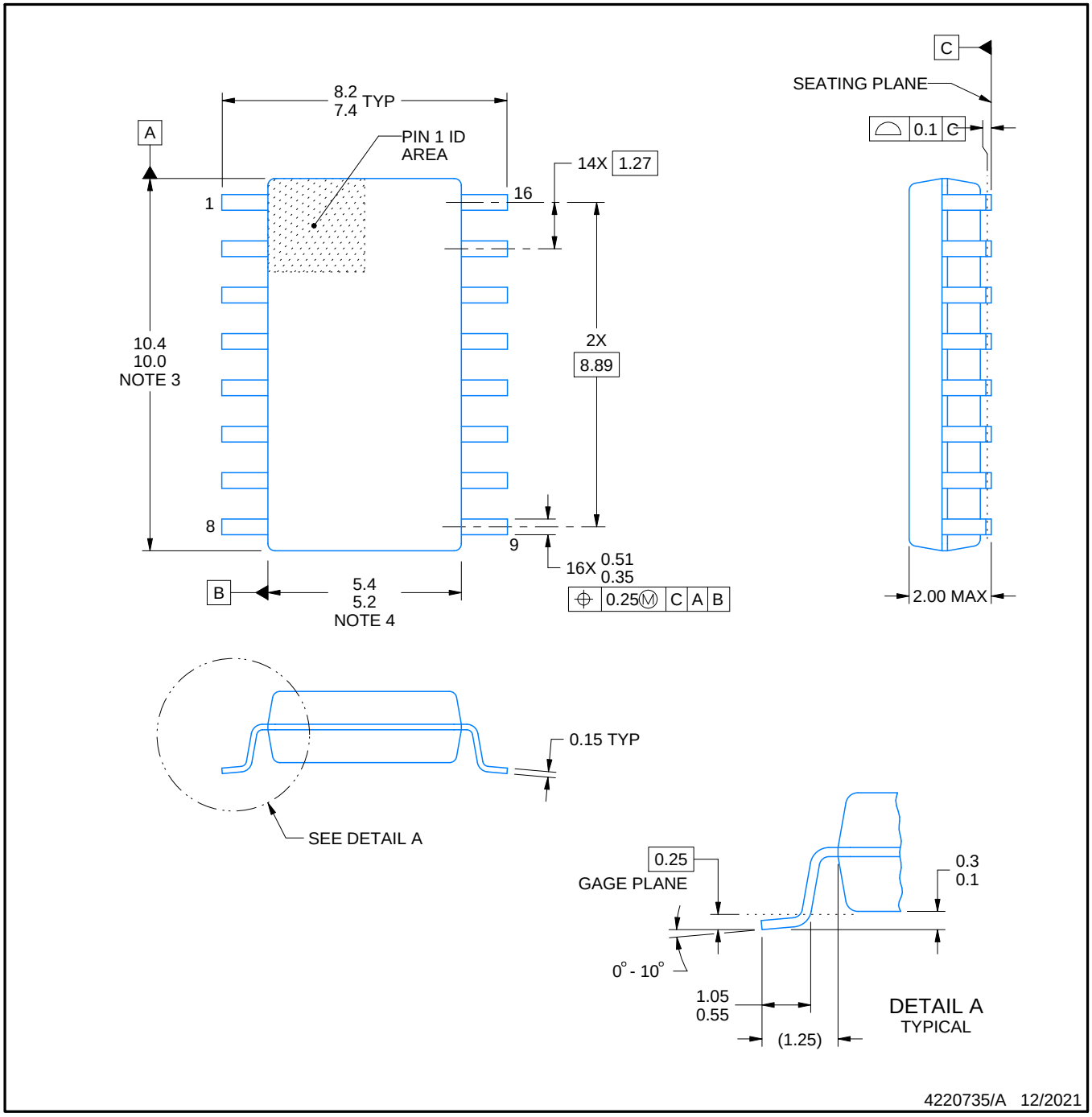


PACKAGE OUTLINE

NS0016A

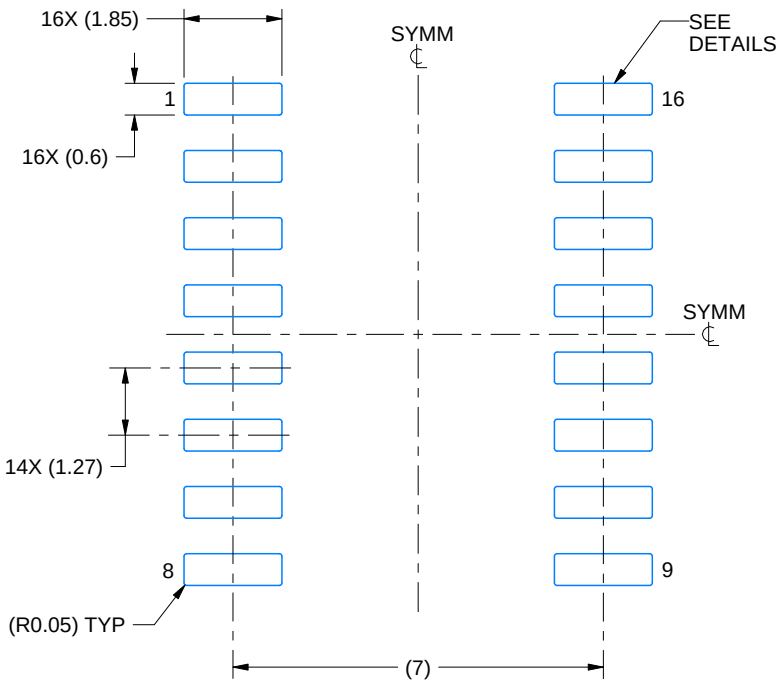
SOP - 2.00 mm max height

SOP

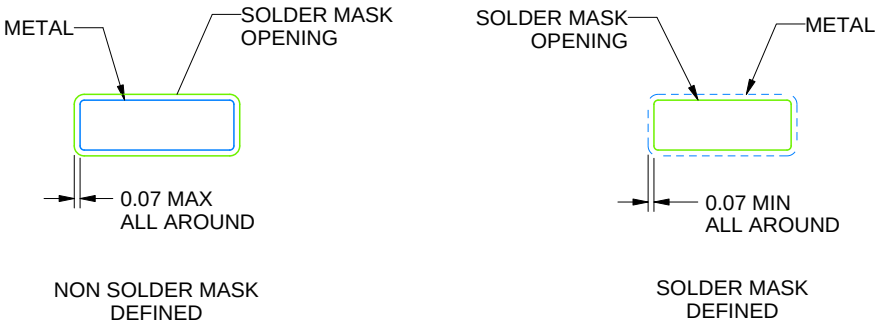


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

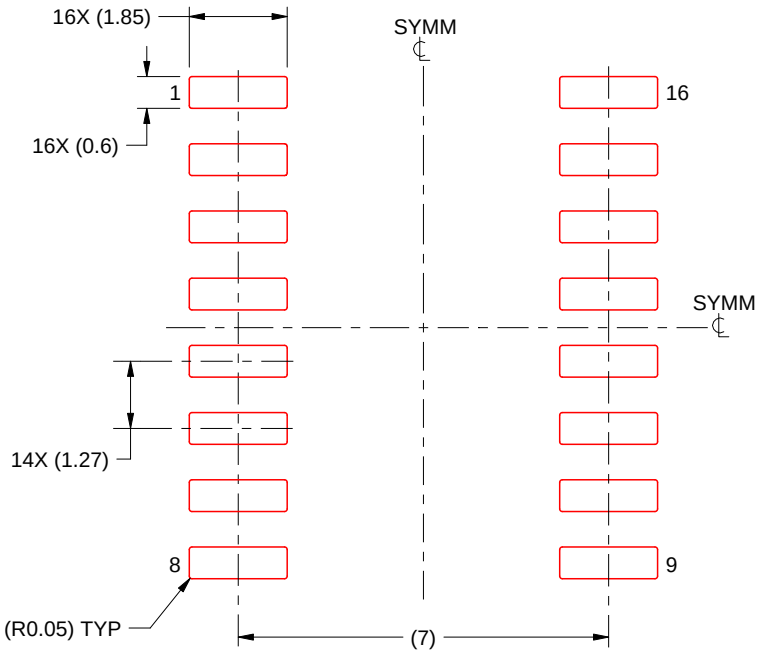
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

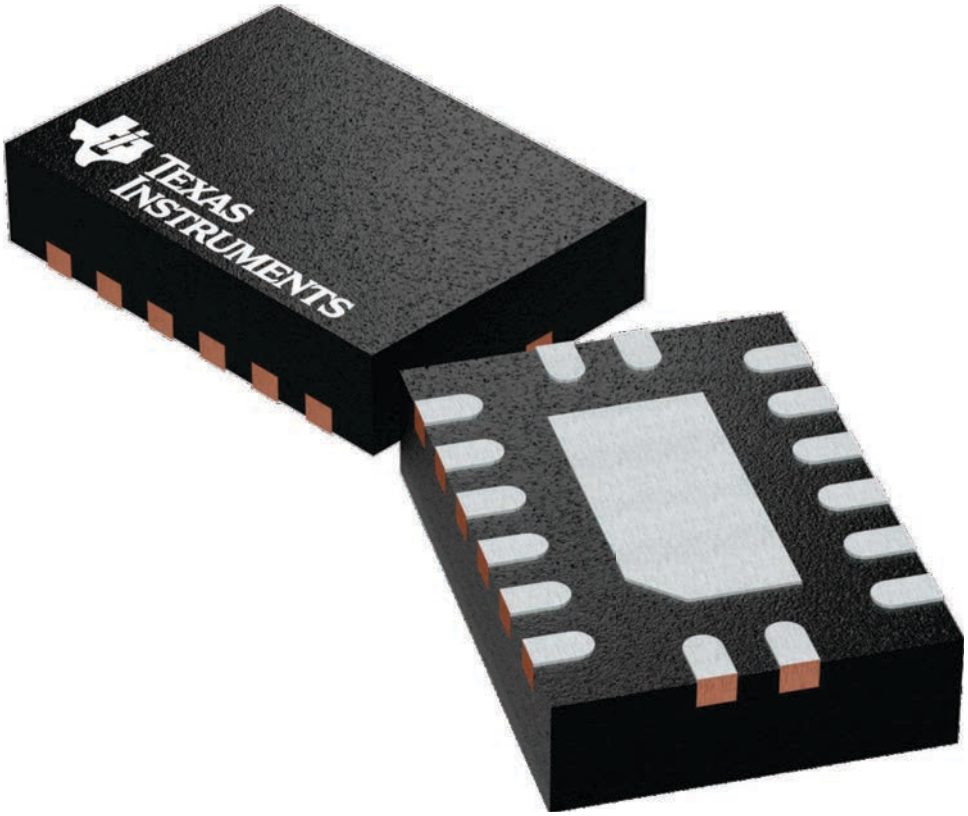
BQB 16

WQFN - 0.8 mm max height

2.5 x 3.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



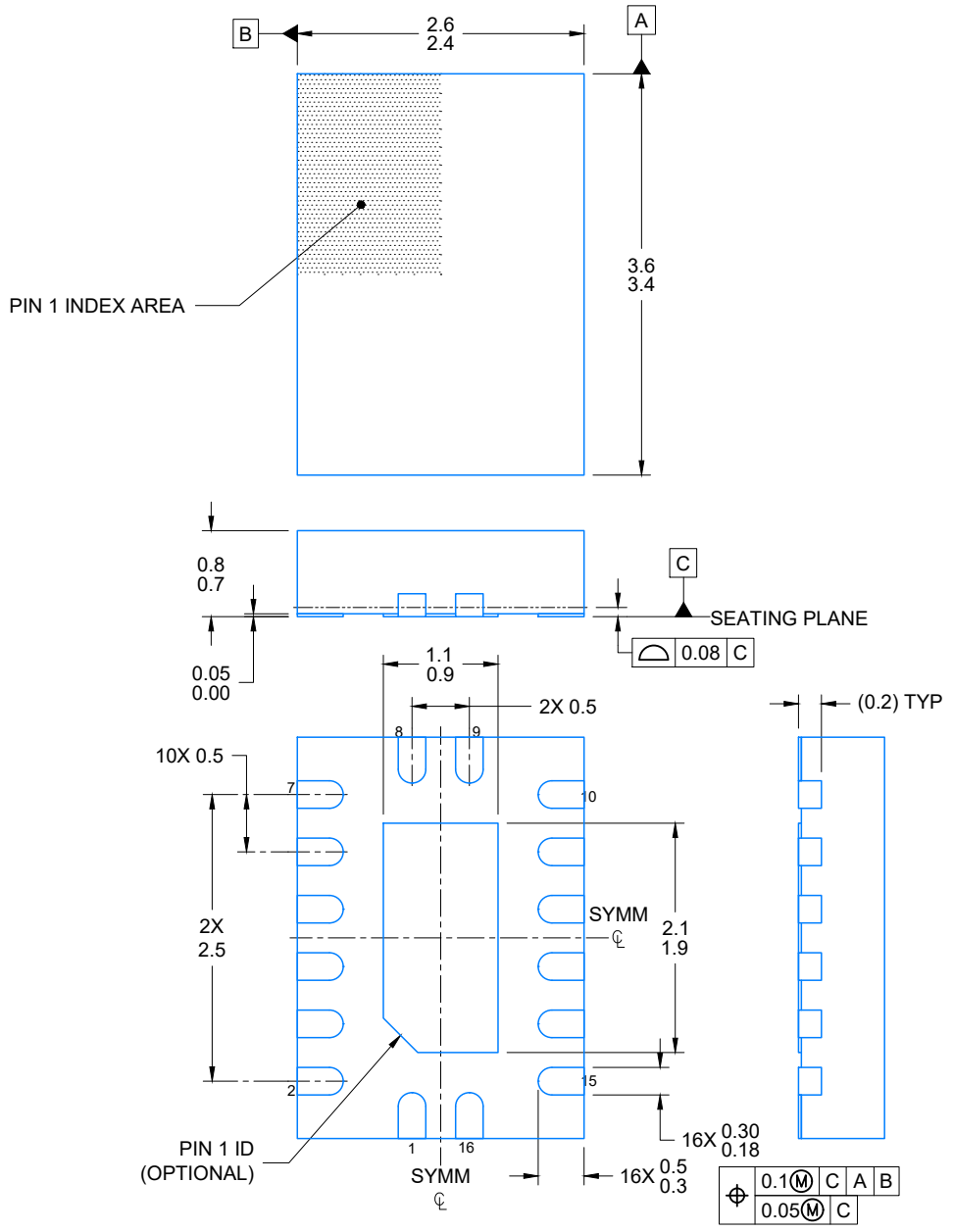
4226161/A

PACKAGE OUTLINE

BQB0016A

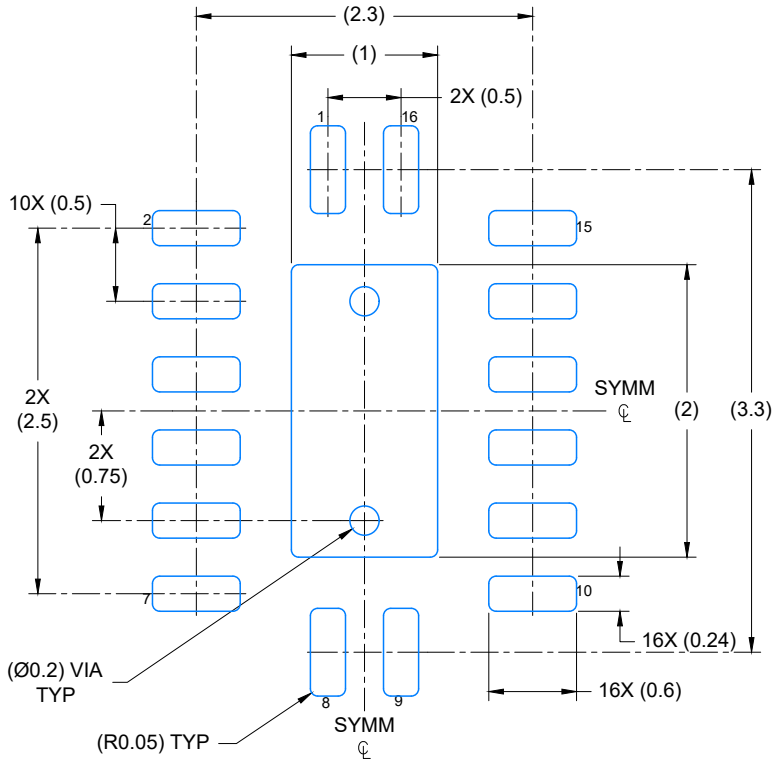
WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD

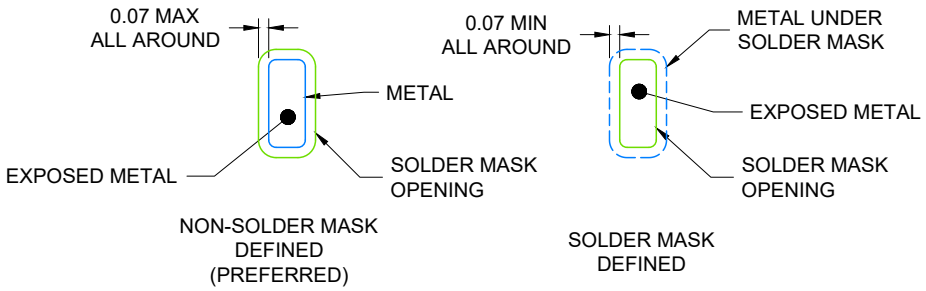


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



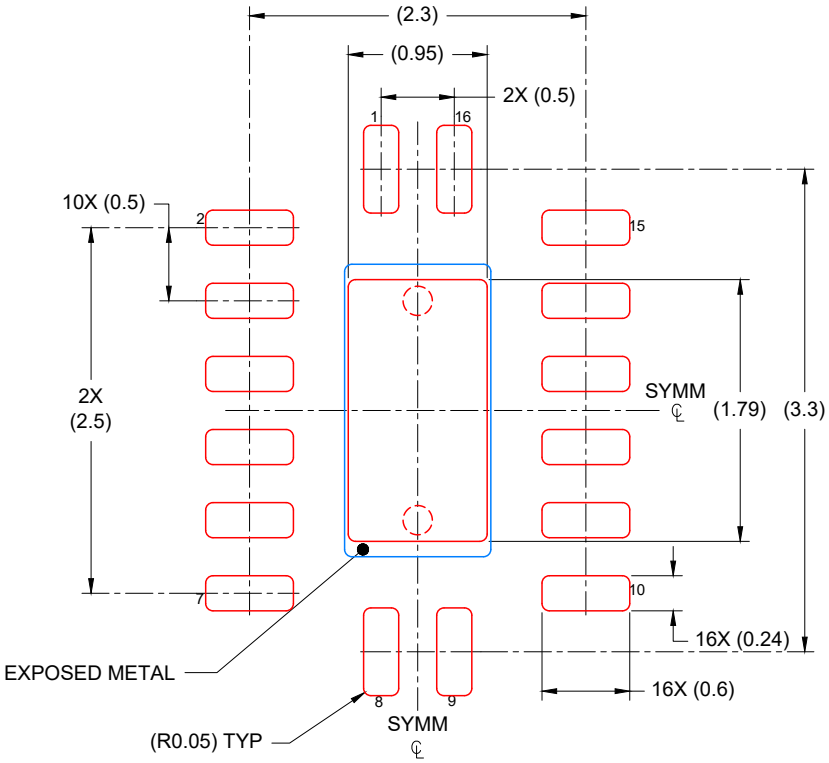
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



4224640/A 11/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

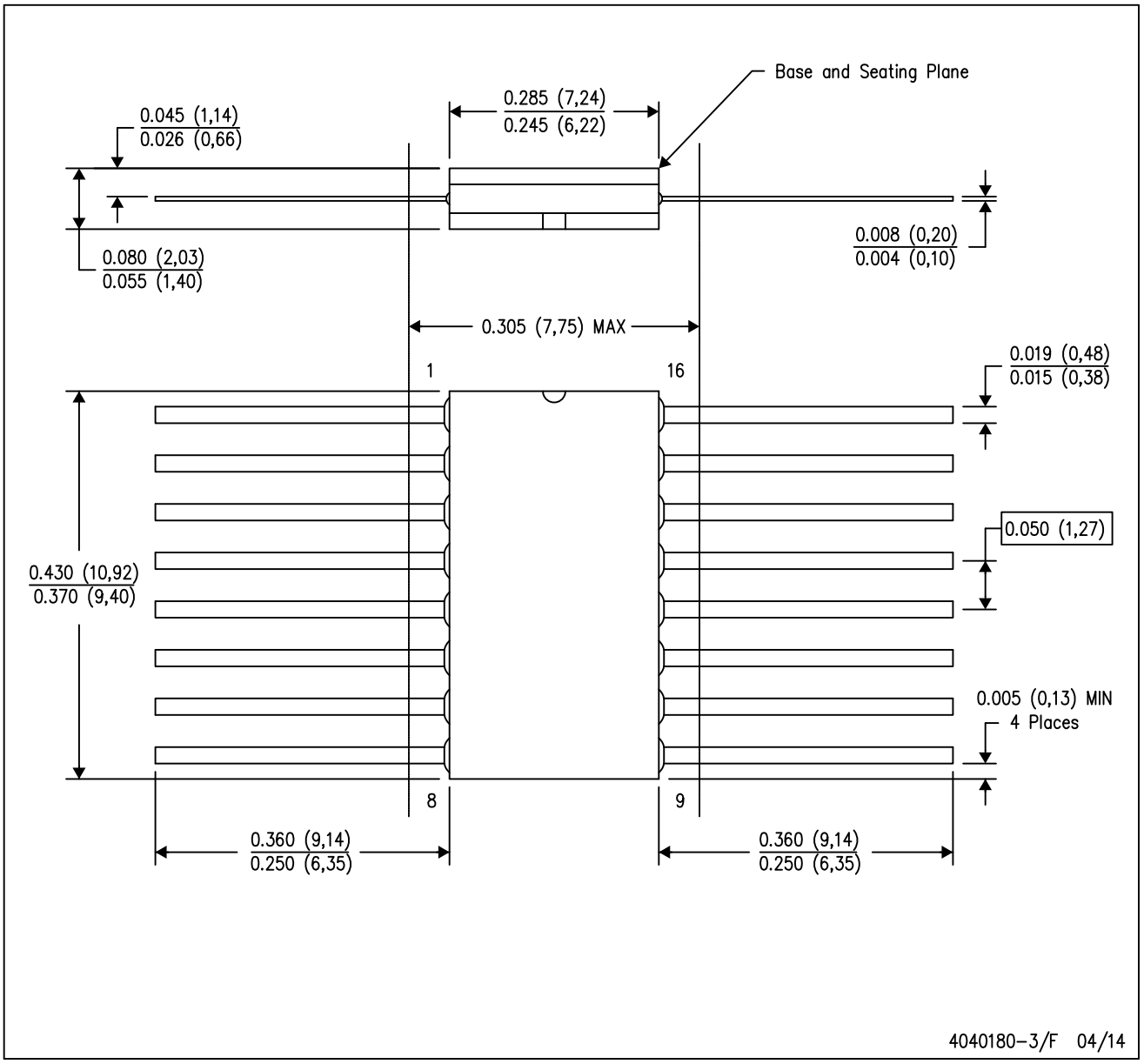
EXPOSED PAD
85% PRINTED COVERAGE BY AREA
SCALE: 20X

4224640/A 11/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

W (R–GDFP–F16) CERAMIC DUAL FLATPACK

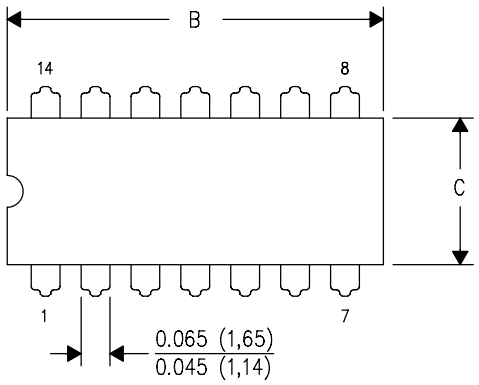


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

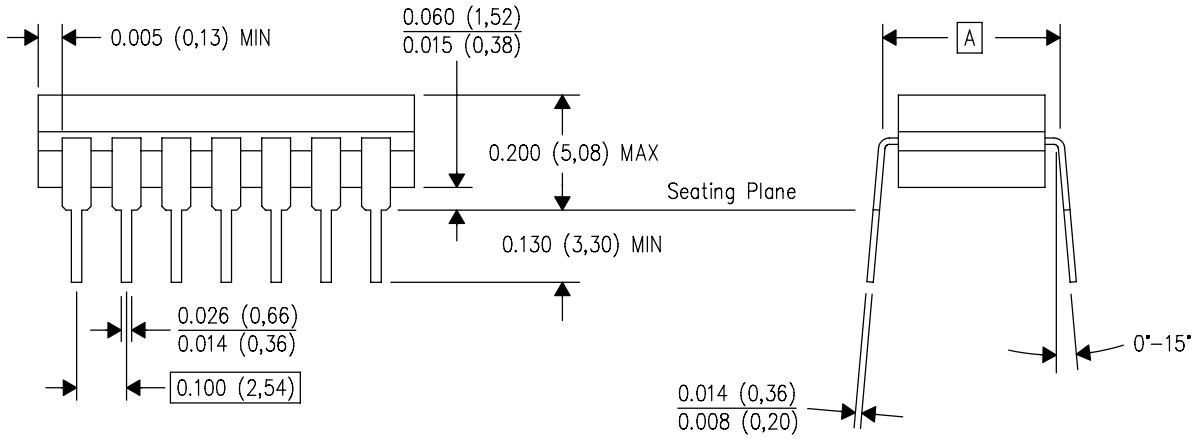
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



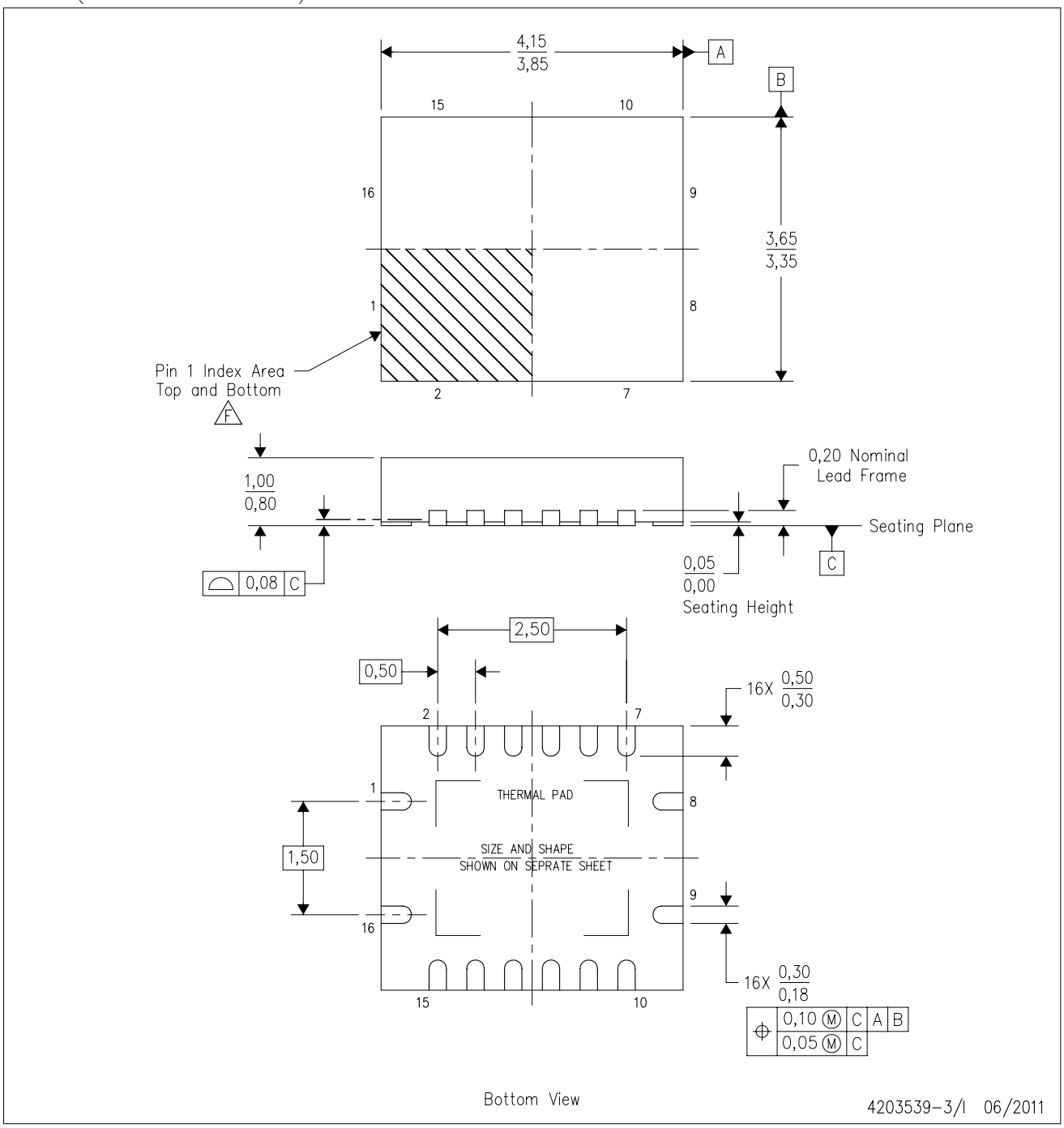
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
G. Package complies to JEDEC MO–241 variation BA.

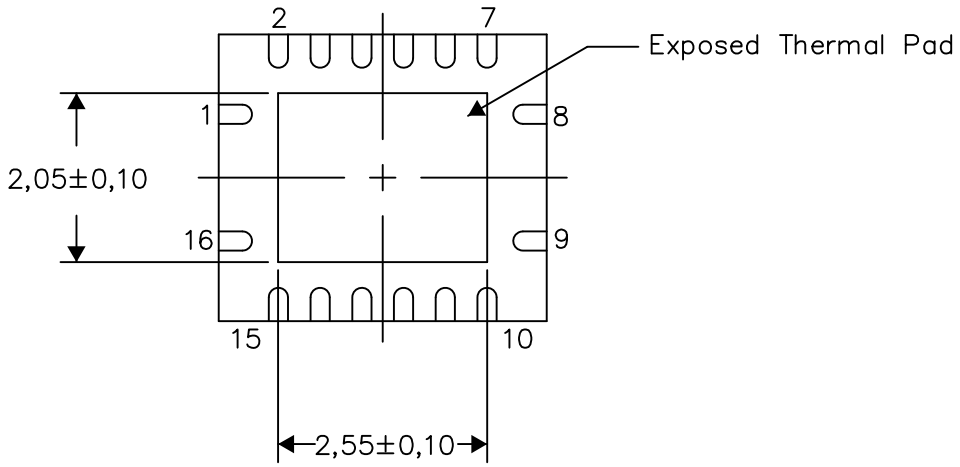
RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



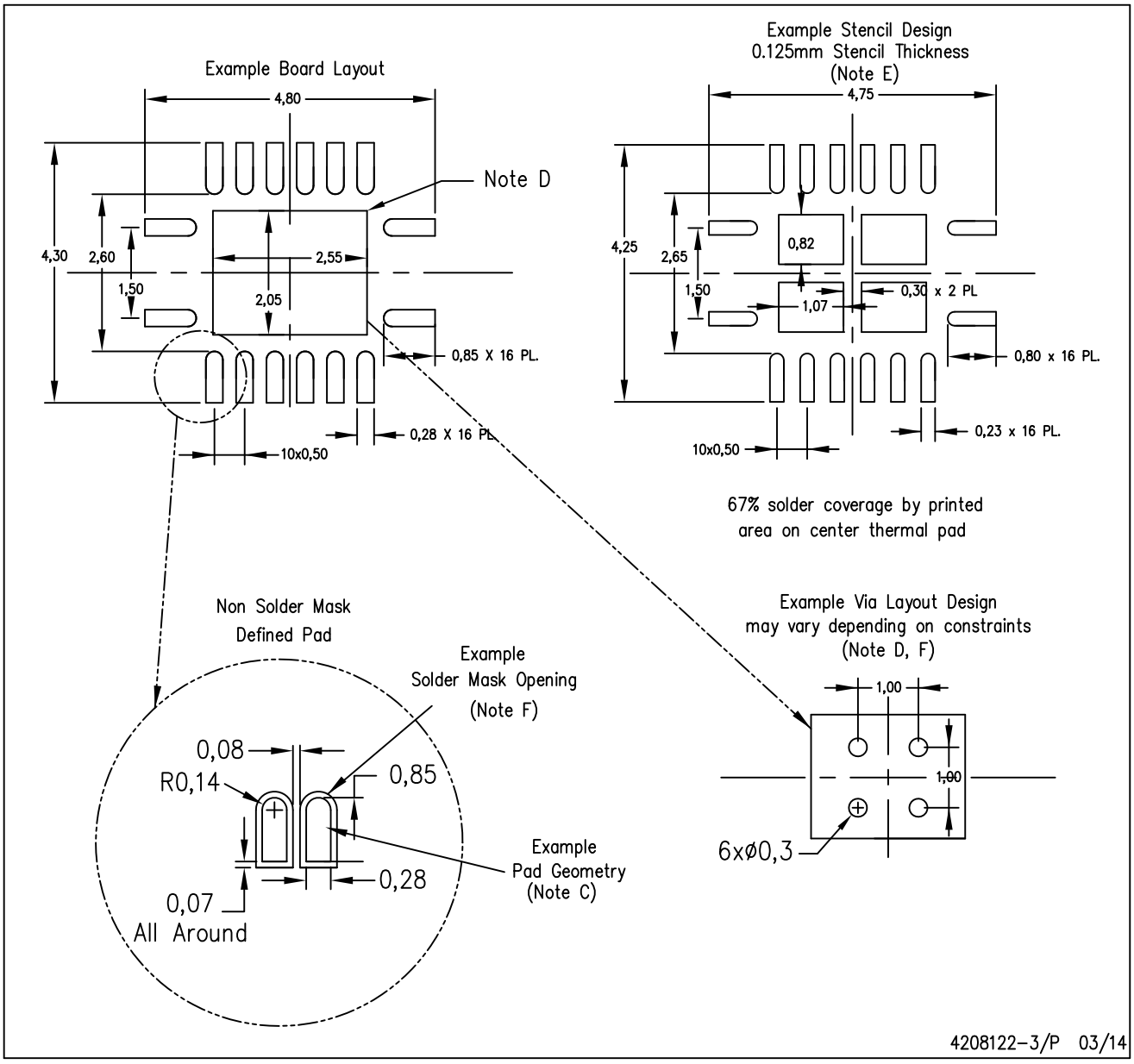
Bottom View

Exposed Thermal Pad Dimensions

4206353–3/P 03/14

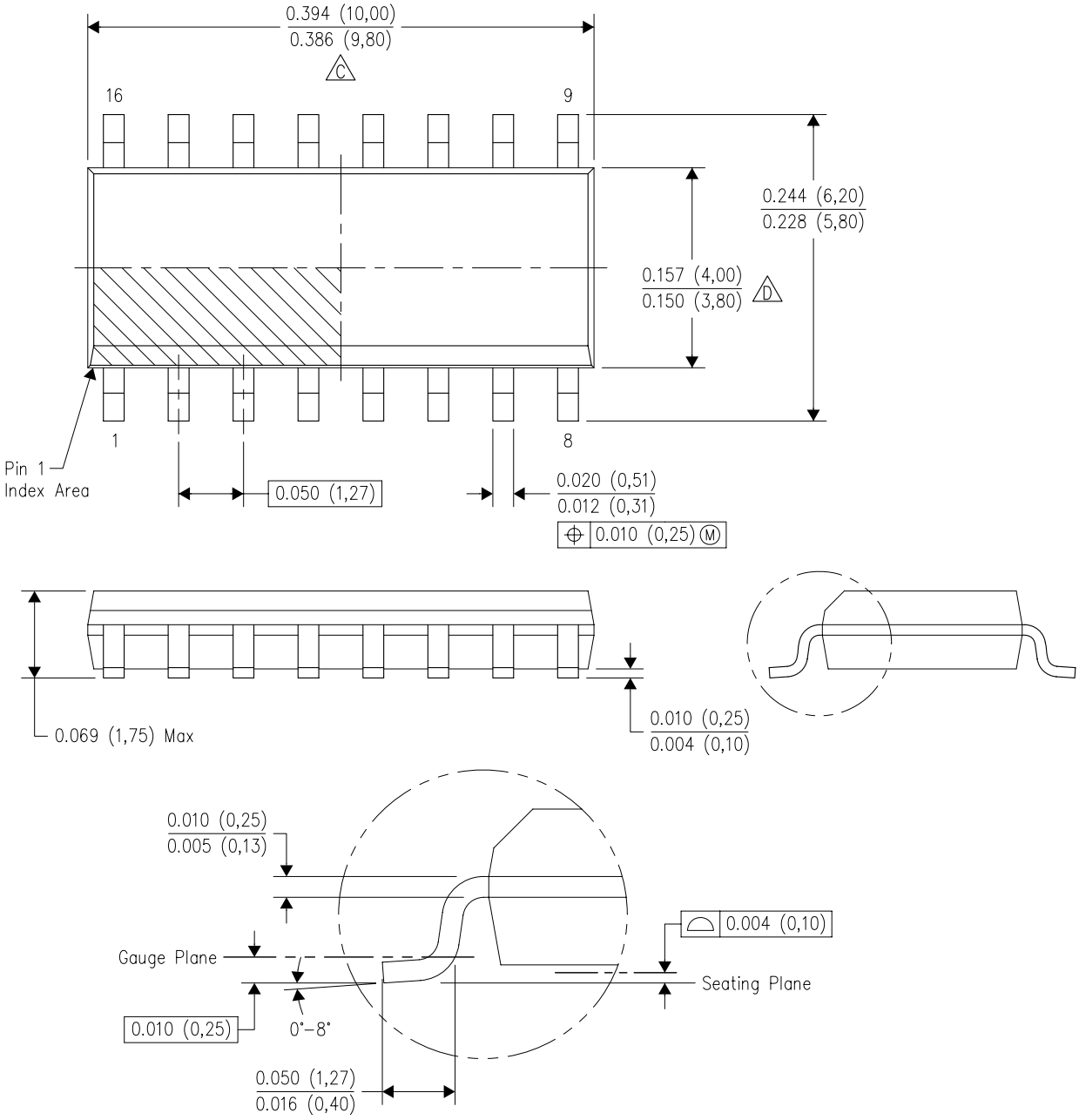
NOTE: All linear dimensions are in millimeters

RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http: //www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



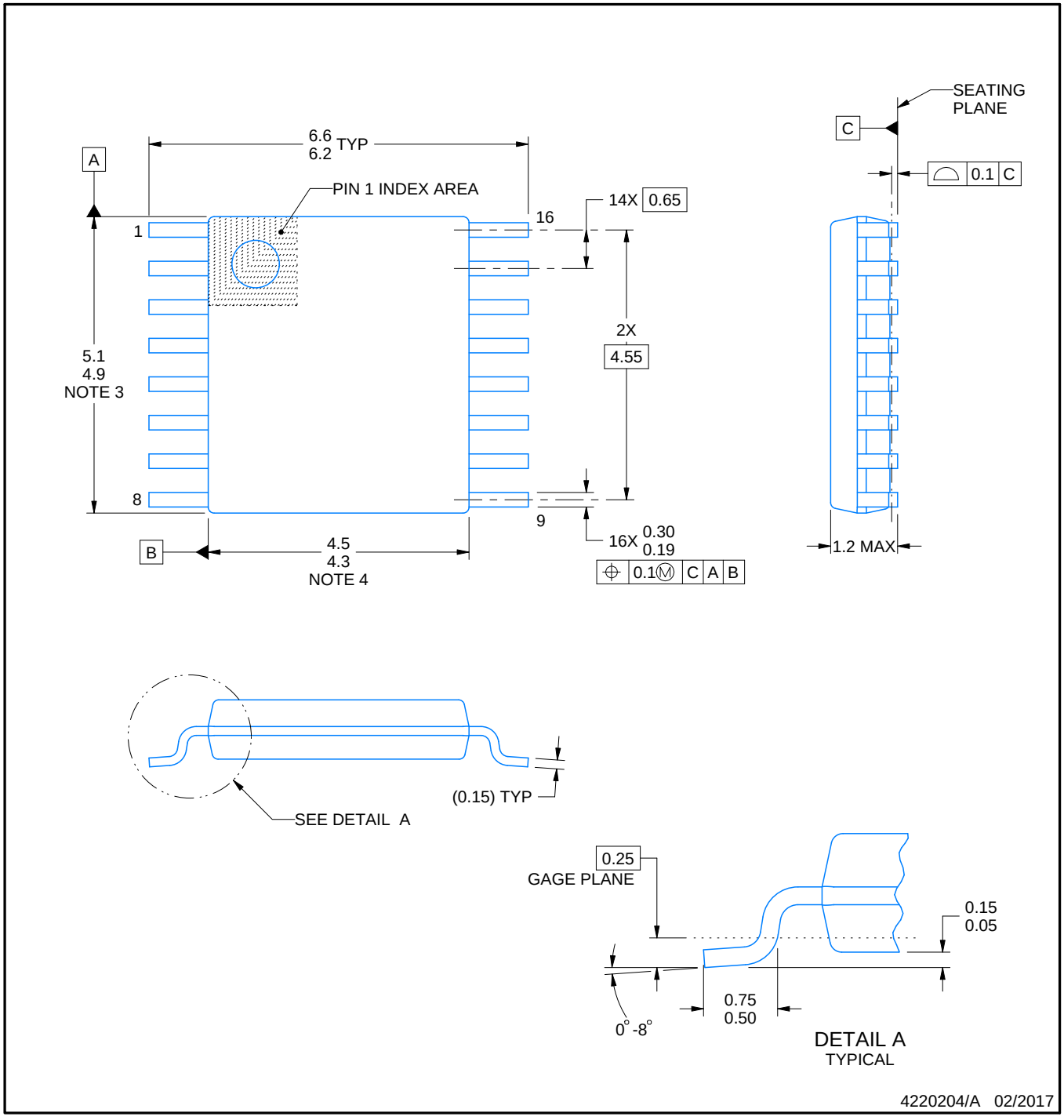
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

PACKAGE OUTLINE

PW0016A

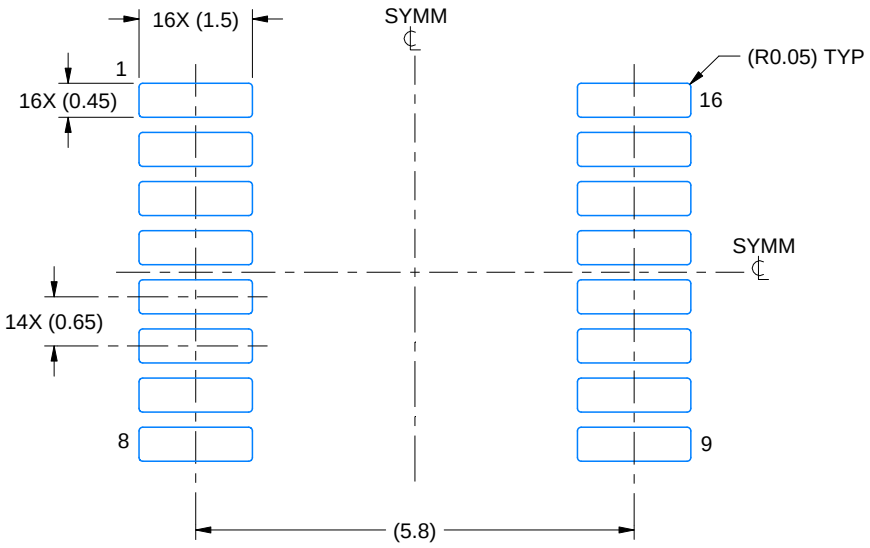
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

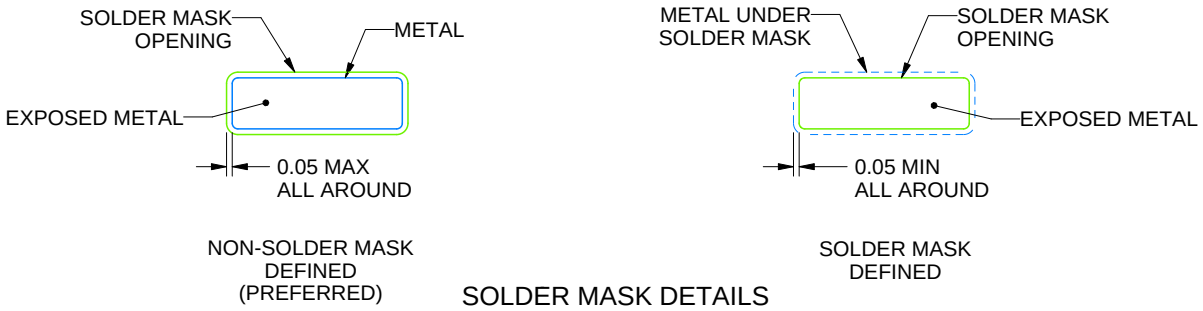


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

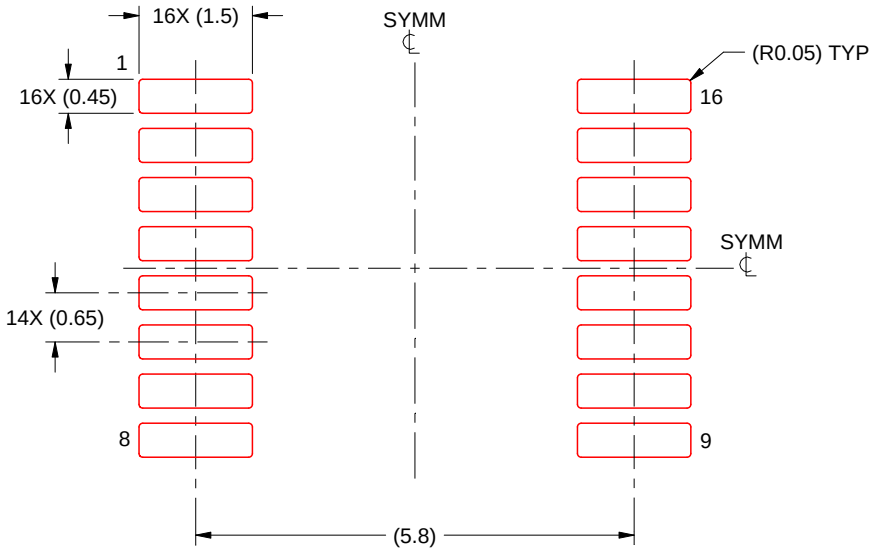


SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

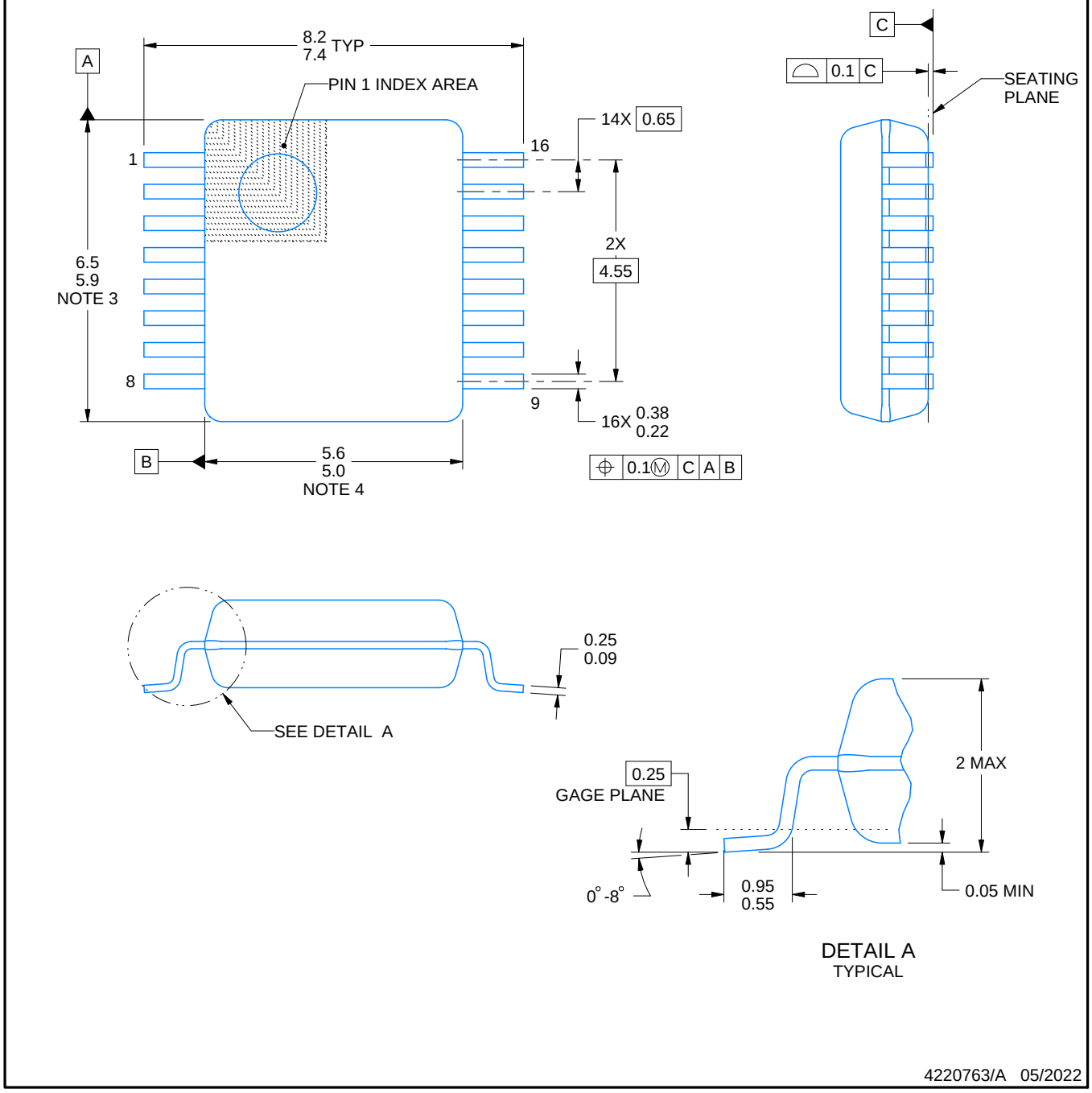
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DB0016A

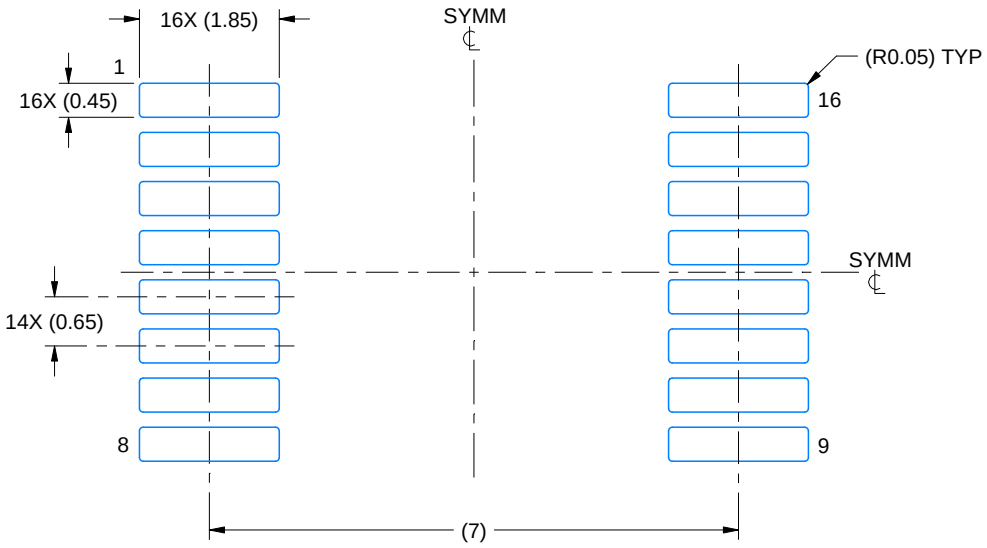
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

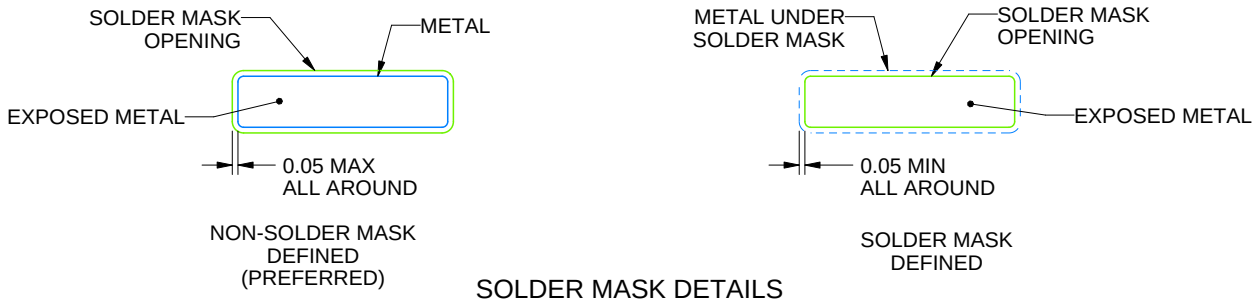


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

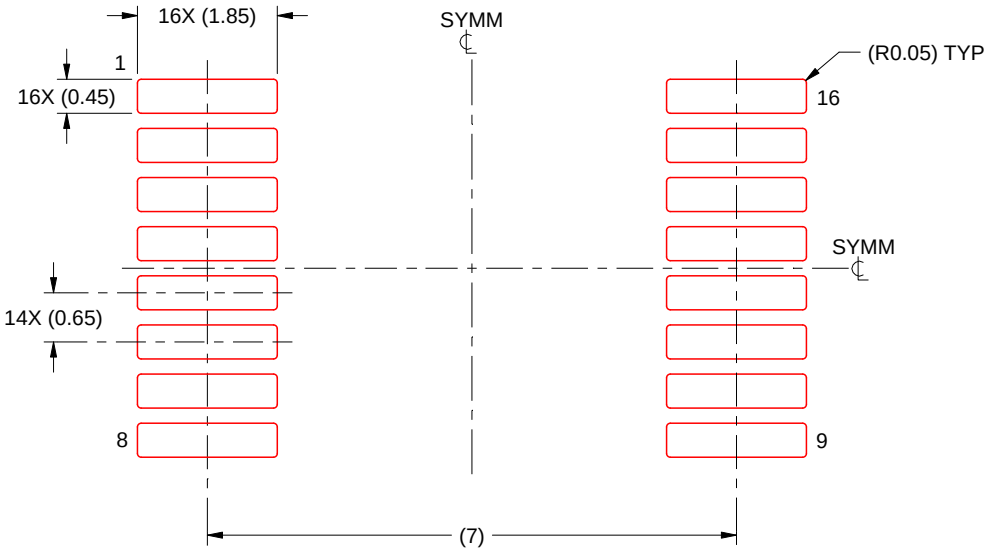


SOLDER MASK DETAILS

4220763/A 05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

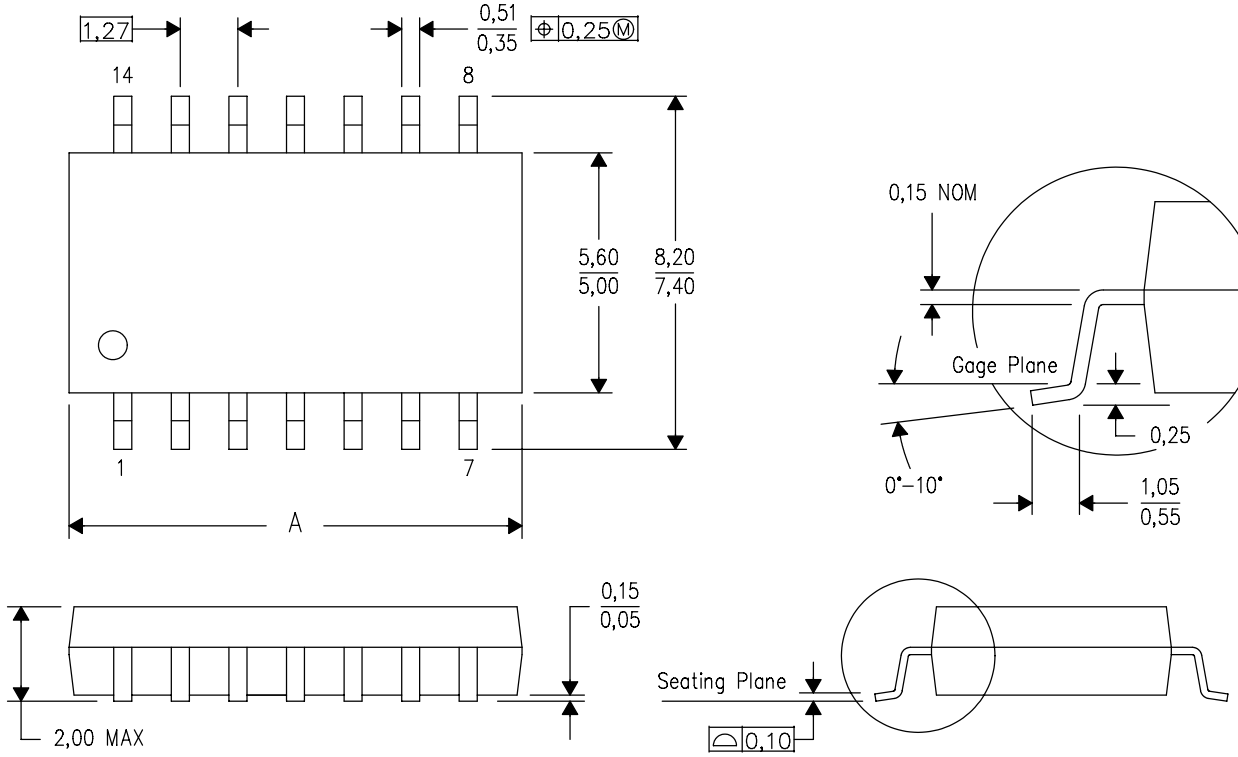
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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